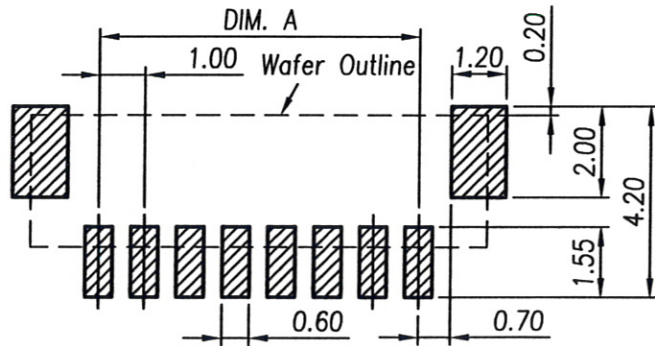
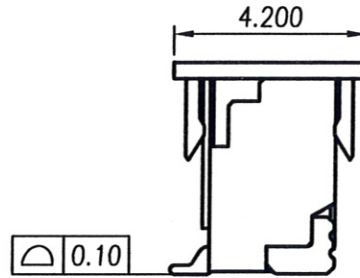
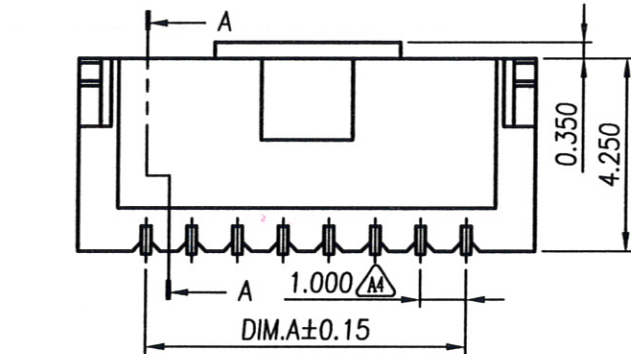


SEC. A-A



RECOMMENDED P.C.B LAYOUT

REV	MODIFICATION	DATE	DRAW
A2	Release To ECN20130915	2013.09.12	Michelle
A3	Release To ECN20140212	2014.02.12	Michelle
A4	Release To ECN20150104	2015.01.09	Michelle

Specification

- 1.Current Rating:1A
- 2.Voltage Rating:50V AC/DC
- 3.Contact Resistance:20mΩ Max.
- 4.Insulation Resistance:100MΩ Min.
- 5.Dielectric Withstanding Voltage:AC250V/Minute
- 6.Operating Temperature:-25°C~+85°C

Material:

- 1.Housing:High Temperature Thermoplastic UL94V-0
- 2.Tab:Copper Alloy T=0.20mm
- 3.Contact Pin:Copper Alloy T=0.20mm
- 4.Cap: High Temperature Thermoplastic UL94V-0

Finish:

- 1.Housing:Nature
- 2.Tab:Tin Plated Over Nickel
- 3.Contact Pin:See P/N Option
- 4.Cap:Nature

Part No.: AS08600 XX X X X 1

- △A3 No. Of Pin Packing
 02~15,20 0:T&R W/Cap 1:T&R
 3:Tube W/Cap 4:Tube
 Plating △AA
 △AA Housing Material 2:Matte Tin Plated Over Nickel
 K:HTN UL94V-0 Nature H.F 3:Gold Flash Over Nickel
 S:HTN UL94V-0 Blue

PIN	DIM. A	DIM. B	DIM. C	PIN	DIM. A	DIM. B	DIM. C	PIN	DIM. A	DIM. B	DIM. C
02	1.00	4.00	2.45	07	6.00	9.00	7.45	12	11.00	14.00	12.45
03	2.00	5.00	3.45	08	7.00	10.00	8.45	13	12.00	15.00	13.45
04	3.00	6.00	4.45	09	8.00	11.00	9.45	14	13.00	16.00	14.45
05	4.00	7.00	5.45	10	9.00	12.00	10.45	15	14.00	17.00	15.45
06	5.00	8.00	6.45	11	10.00	13.00	11.45	20	19.00	22.00	20.45



RoHS Compliant

金上達科技股份有限公司
GOLDENSUNDA TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED: .x± 0.35, .x'± 2', .xx± 0.25, .x'± 1', .xxx± 0.15, .xx'± 0.5'

PROJ. TITLE: Wire To Board Wafer 1.00mm 180° SMT Single Row

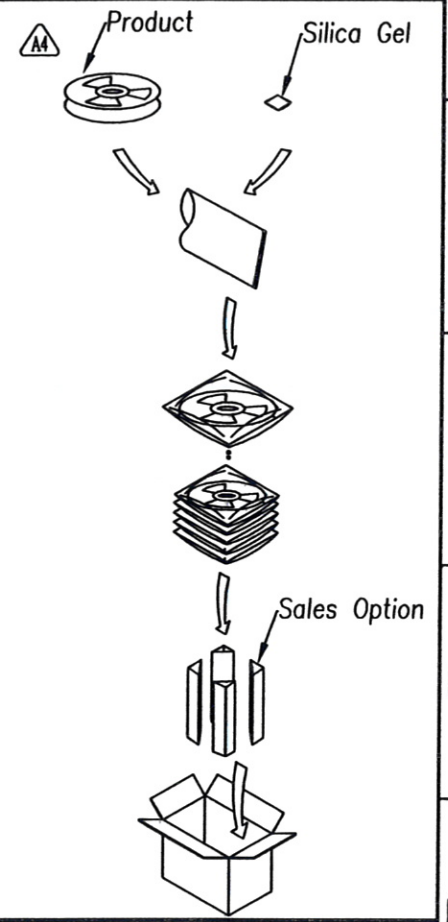
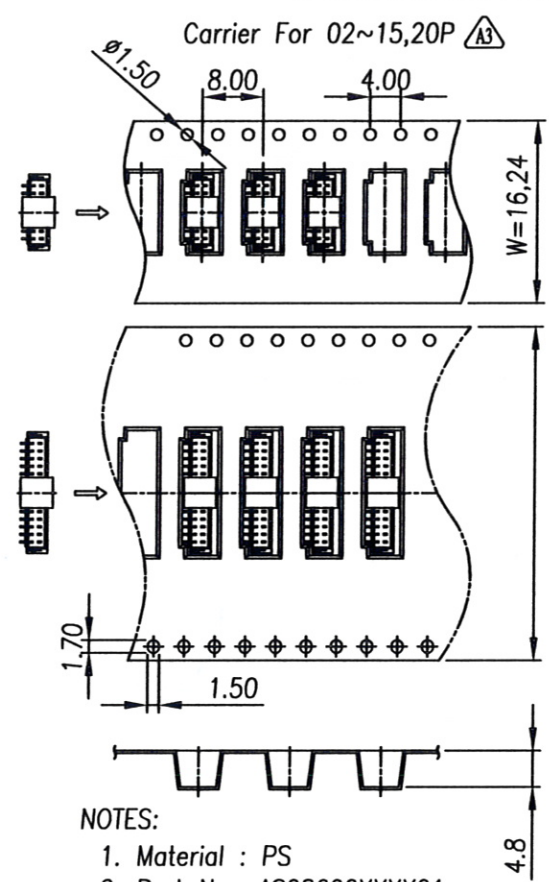
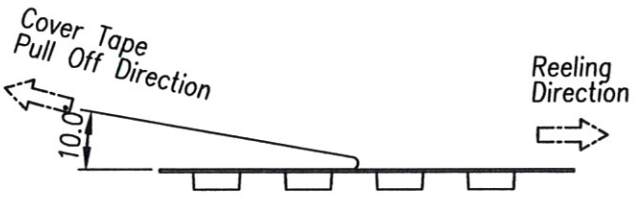
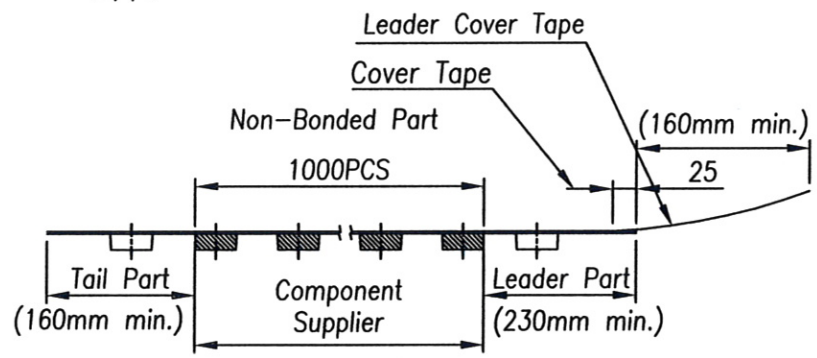
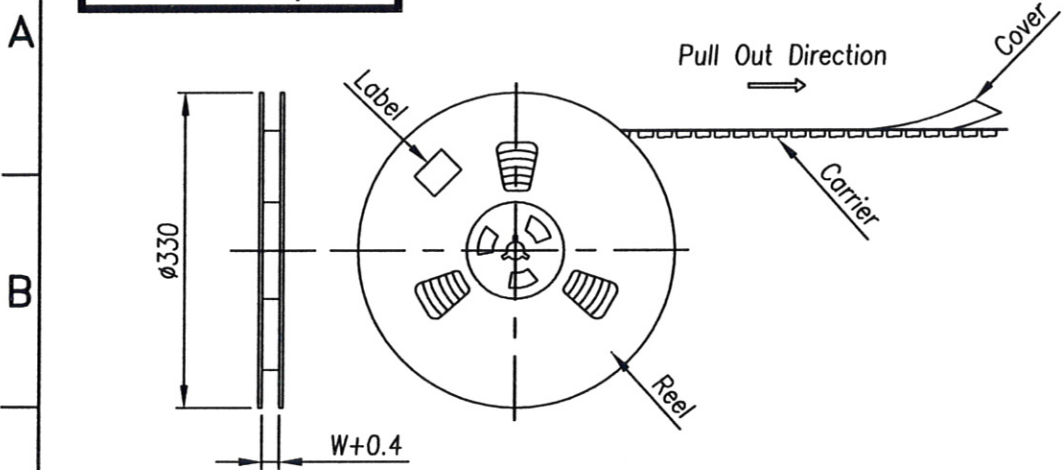
APR. C.F.Liao 20150109 PART NO. AS08600XXXXX1 DWG NO. AS08600XXXXX1

CHK. Abel 20150109 UNITS: mm CUSTOMER DRAWING

DRAW. Michelle 20150109 SIZE: A4 SCALE 6:1 SHEET 1 / 2 REV A4

RoHS Compliant

REV	MODIFICATION	DATE	DRAW
A2	Release To ECN20130915	2013.09.12	Michelle
A3	Release To ECN20140212	2014.02.12	Michelle
A4	Release To ECN20150104	2015.01.09	Michelle



- NOTES:
 1. Material : PS
 2. Part No.: AS08600XXXX01

PIN NO.	W	PCS/REEL
02 ~ 05	16	1000
06 ~ 13	24	
14~15,20	44	

發行
104. 1. 09
文管中心

金上達科技股份有限公司
GOLDENSUNDA TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ.	TITLE: Wire To Board Wafer 1.00mm 180° SMT Single Row	
.x± 0.35	.x.* 2'	APR. C.F.Liao 20150109	PART NO. AS08600XXXXX1	DWG NO. AS08600XXXXX1
.xx± 0.25	.x.* 1'	CHK. Abel 20150109	UNITS: mm	CUSTOMER DRAWING
.xxx± 0.15	.xx.* 0.5'	DRA. Michelle 20150109	SIZE: A4	SCALE Free
			SHEET 2 / 2	REV A4